

FEATURES 特征

- Small chip suitable for surface mounting.
小尺寸，可表面贴装
- Large inductance with ferrite material.
铁氧体材料具有大电感量
- Single-sided package.
单面封装
- Operating Temp : -45°C~+85°C(Including self heating).
工作温度范围:-45°C~+85°C(包括自身温度上升)



APPLICATIONS 用途

- Mobile phones and other electronic devices.
移动电话等电子设备
- Bluetooth modules and TWS earphones.
蓝牙模块、TWS 耳机

PART NUMBERING 产品型号

AHW	1608	FE	100	K	T	F
①	②	③	④	⑤	⑥	⑦

① Series Name	
AHW	Wire Wound Chip Inductor

② External Dimensions	
	1608[0603]
	2012[0805]

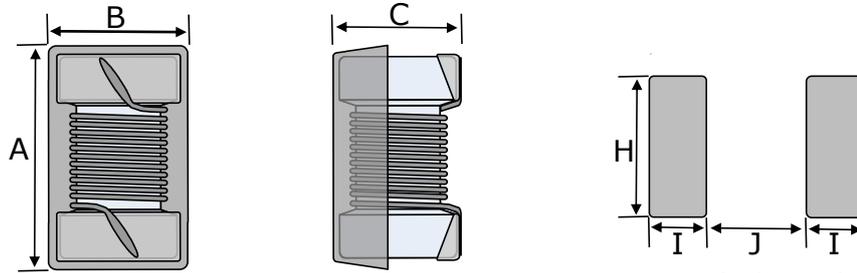
③ Feature Type	
FE	Ferrite core

④ Nominal Inductance	
Code (example)	Nominal Inductance [μH]
1R0	1
100	10
101	100

⑤ Inductance Tolerance	
J	5%
K	10%
M	20%

⑥ Packaging	
T	Tape & Reel

⑦ HSF Products	
F	Hazardous Substance Free Products

DIMENSIONS & RECOMMENDED LAND PATTERN 尺寸及推荐焊盘


Recommended Land Pattern

Unit: mm

Series	Dimensions			Recommended Land Pattern		
	A	B	C	I	H	J
	Max.			Typ.		
AHW1608FE	1.80	1.25	1.10	0.64	1.02	0.64
AHW2012FE	2.40	1.73	1.55	1.02	1.78	0.76

ELECTRICAL CHARACTERISTICS 特性规格表

● AHW1608FE Series

Part Number	Inductance	Inductance Tolerance	L Test Freq.	Quality Factor	Self-resonant Frequency	DC Resistance	Rated Current
				Min.	Min.	Max.	Typ.
Unit	μH	-	MHz	-	MHz	Ω	mA
Symbol	L	-	Freq.	Q	S.R.F	DCR	Irms
AHW1608FE1R0□TF	1.0	K,M	7.9	16	250	0.41	700
AHW1608FE1R5□TF	1.5	K,M	7.9	16	160	0.52	600
AHW1608FE1R8□TF	1.8	K,M	7.9	16	121	0.56	580
AHW1608FE2R2□TF	2.2	K,M	7.9	16	103	0.72	580
AHW1608FE2R7□TF	2.7	K,M	7.9	16	72	0.81	500
AHW1608FE3R3□TF	3.3	K,M	7.9	16	66	0.91	500
AHW1608FE3R9□TF	3.9	K,M	7.9	16	61	1.08	460
AHW1608FE4R7□TF	4.7	K,M	7.9	16	51	0.97	420
AHW1608FE5R6□TF	5.6	K,M	7.9	16	47	1.43	380
AHW1608FE6R8□TF	6.8	K,M	7.9	16	43	1.95	340
AHW1608FE8R2□TF	8.2	K,M	7.9	16	40	2.18	300
AHW1608FE100□TF	10	J,K,M	2.5	14	36	2.4	280
AHW1608FE120□TF	12	J,K,M	2.5	14	32	2.96	260
AHW1608FE150□TF	15	J,K,M	2.5	14	29	3.38	220
AHW1608FE180□TF	18	J,K,M	2.5	14	28	3.77	220
AHW1608FE220□TF	22	J,K,M	2.5	14	24	4.69	200
AHW1608FE270□TF	27	J,K,M	2.5	14	20	6.76	140
AHW1608FE330□TF	33	J,K,M	2.5	14	15	8.58	120
AHW1608FE470□TF	47	J,K,M	2.5	14	5	12	100

ELECTRICAL CHARACTERISTICS 特性规格表
● AHW2012FE Series

Part Number	Inductance	Inductance Tolerance	L Test Freq.	Quality Factor	Self-resonant Frequency	DC Resistance	Rated Current
				Min.	Min.	Max.	Typ.
Unit	μH	-	MHz	-	MHz	Ω	mA
Symbol	L	-	Freq.	Q	S.R.F	DCR	Irms
AHW2012FER68□TF	0.68	K,M	7.9	14	765	0.19	1480
AHW2012FE1R0□TF	1.0	K,M	7.9	14	208	0.17	1350
AHW2012FE1R2□TF	1.2	K,M	7.9	14	208	0.17	1180
AHW2012FE1R5□TF	1.5	K,M	7.9	14	130	0.22	1080
AHW2012FE1R8□TF	1.8	K,M	7.9	14	112	0.26	1060
AHW2012FE2R2□TF	2.2	K,M	7.9	12	80	0.31	1040
AHW2012FE3R3□TF	3.3	K,M	7.9	12	50	0.36	870
AHW2012FE4R7□TF	4.7	K,M	7.9	14	51	0.56	840
AHW2012FE5R6□TF	5.6	K,M	7.9	12	42	0.65	640
AHW2012FE6R8□TF	6.8	K,M	7.9	14	35	0.88	700
AHW2012FE8R2□TF	8.2	K,M	7.9	13	33	0.94	570
AHW2012FE100□TF	10	J,K,M	2.5	14	25	1.17	560
AHW2012FE120□TF	12	J,K,M	2.5	14	30	1.5	390
AHW2012FE150□TF	15	J,K,M	2.5	15	28	1.82	380
AHW2012FE180□TF	18	J,K,M	2.5	15	27	2.01	360
AHW2012FE220□TF	22	J,K,M	2.5	15	20	2.29	340
AHW2012FE470□TF	47	J,K,M	2.5	14	15	4.42	280
AHW2012FE560□TF	56	J,K,M	2.5	14	10	5.75	150
AHW2012FE680□TF	68	J,K,M	2.5	14	10	5.9	140
AHW2012FE820□TF	82	J,K,M	2.5	14	10	9.75	100
AHW2012FE101□TF	100	J,K,M	1	10	5	9.75	100

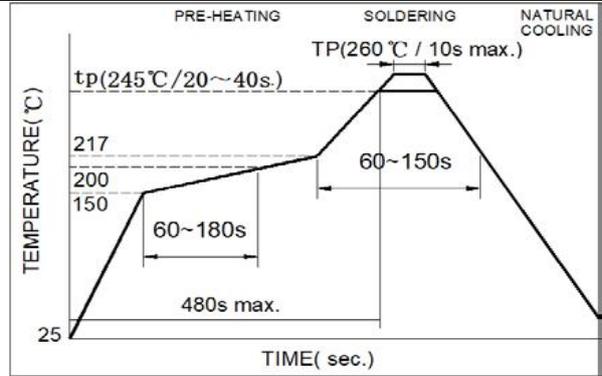
- Rating DC current: Temperature rise(ΔT) is 40°C approximately at Irms.
- Storage temp.: -10°C ~ +40°C R.H.: 60% Max.
- The 1608FE and 2012FE with color point Marking can be provided upon customer's request.

RECOMMENDED SOLDERING TECHNOLOGIES 回流焊建议

Re-flow Soldering (Lead Free)

- ◆ Preheat circuit and products to 150°C.
- ◆ 260°C tip temperature (max).
- ◆ Reflow times: no more than 2 times.
- ◆ Solder paste thickness: the best 0.08mm is ,but max is 0.1mm.

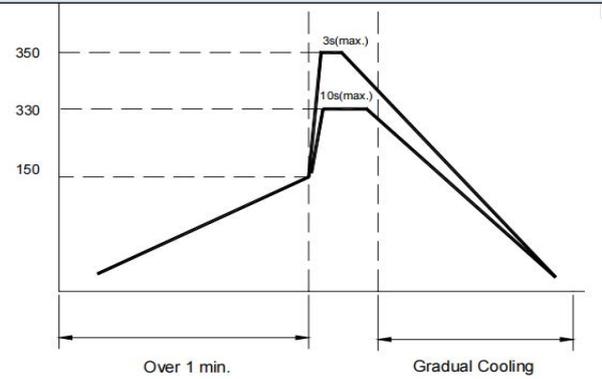
Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.



Hand Soldering

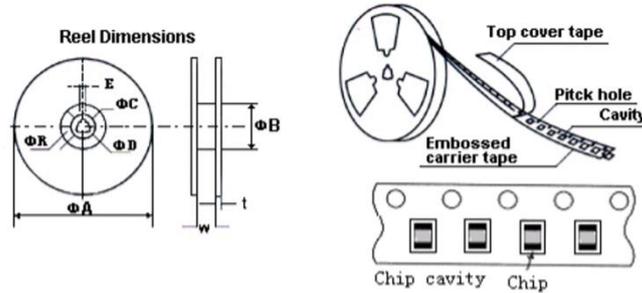
- ◆ Use a 20 watt soldering iron with tip diameter of 1.0mm.
- ◆ Limit soldering time to 3 sec.

Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.

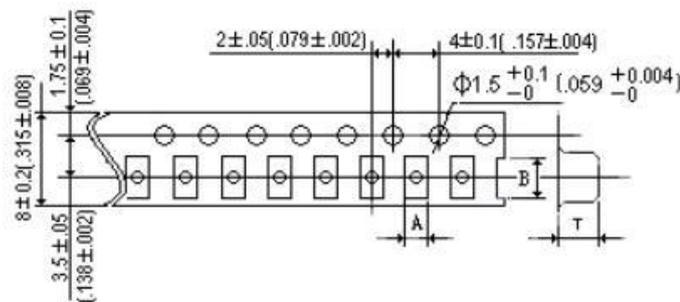


PACKAGING 包装

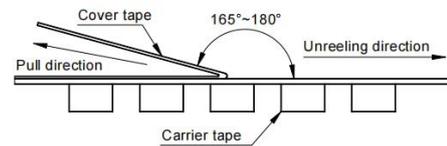
- Packaging (unit: mm)



Polystyrene Tape



- Peeling off force
- Pull strength 1608~2012:20g~80g.
- Speed of peeling off:300mm/min ±10%.



Tape	A	B	C	ΦA	ΦB	ΦC	ΦD	E	W	t
	Typ.									
AHW1608FE	1.15	1.83	0.95	178	60	13	21	2	8.4	2
AHW2012FE	1.9	2.4	1.45	178	60	13	21	2	8.4	2

- Carton Dimensions and Packing Quantity:

Product Series	Quantity / Reel	Inner Carton Quantity	Outer Carton Quantity
AHW1608FE	4000Pcs	40K Pcs	240K Pcs
AHW2012FE	2000Pcs	20K Pcs	160K Pcs

PRECAUTIONS ON USE 使用注意事项

● Precautions on Use.

- 1. Always wear static control bands to protect against ESD.
- 2. Any devices used with the products (soldering irons, measuring instruments) should be properly grounded.
- 3. Keep bare hands and metal conductors (i.e., metal desk) away from electrodes or conductive areas that lead to electrodes.
- 4. Preheat when soldering.
- 5. Don't apply current in excess of the rated current value. It may reduce the impedance or inductance, or cause damage to components due to over-current.
- 6. For magnetic products, keep clear of anything that may generate magnetic fields such as speakers and coils. Use non-magnetic tweezers when handling the chips.
- 7. When soldering, the electrical characteristics may be varied due to hot energy and mechanical stress.
- 8. When coating products with resin, the relatively high resin curing stress may change the electrical characteristics. For exterior coating, select resin carefully so that electrical and mechanical performance of the product is not affected. Before using, please evaluate reliability with the product mounted in your application set.
- 9. When mount chips with adhesive in preliminary assembly, do appropriate check before the soldering stage, i.e., the size of land pattern, type of adhesive, amount applied, hardening of the adhesive on proper usage and amounts of adhesive to use.
- 10. Mounting density: Add special attention to radiating heat of products when mounting other components nearby. The excessive heat by other products may cause deterioration at joint of this product with substrate.
- 11. Since some products are constructed like an open magnetic circuit, narrow spacing between components may cause magnetic coupling.
- 12. Please do not give the product any excessive mechanical shocks in transportation.
- 13. Please do not touch wires by sharp terminals such as tweezers to avoid causing any damage to wires.
- 14. Please do not add any shock and power to the soldered product to avoid causing any damage to chip body.
- 15. Please do not touch the electrodes by naked hand as the solderability of the external electrodes may deteriorate by grease or oil on the skin.

SAFETY REMINDERS 注意事项**SAFETY REMINDERS**

The Company shall not guarantee the suitability, performance, or quality for the following applications that require a high level of safety and reliability, or where equipment failure, malfunction, or abnormal operation may cause damage to human life, physical well-being, or property, and may have significant social impacts (hereinafter referred to as "specific applications"). If you intend to use this product in the application scenarios listed below, or if you have special requirements exceeding the scope or conditions specified in each product catalog, please contact us.

- (1) Aerospace/aviation equipment
- (2) Transportation equipment (cars, electric trains, ships, etc.)
- (3) Medical equipment
- (4) Power-generation control equipment
- (5) Atomic energy-related equipment
- (6) Seabed equipment
- (7) Transportation control equipment
- (8) Public information-processing equipment
- (9) Military equipment
- (10) Electric heating apparatus, burning equipment
- (11) Disaster prevention/crime prevention equipment
- (12) Safety equipment
- (13) Other applications that are not considered general-purpose applications

When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.